

Description

The AP90N08NF uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 10V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = 85V I_{D} = 95A$

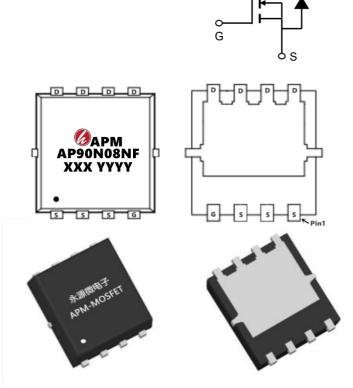
 $R_{DS(ON)} < 5.2 \text{m}\Omega \text{ V}_{GS} = 10 \text{V (Type: } 4.5 \text{m}\Omega)$

Application

Battery protection

Load switch

Uninterruptible power supply



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP90N08NF	PDFN5*6-8L	AP90N08NF XXX YYYY	5000

Absolute Maximum Ratings (T_c=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	85	V
VGS	Gate-Source Voltage	±20	V
ID@TC=25℃	Continuous Drain Current, VGS @ 10V	95	Α
ID@TC=100°C	Continuous Drain Current, VGS @ 10V	75	Α
IDM	Pulsed Drain Current	480	Α
EAS	Single Pulse Avalanche Energy 560		mJ
IAS	Avalanche Current	43.4	Α
PD@TC=25℃	Total Power Dissipation4 180		W
TSTG	Storage Temperature Range -55 to 150		$^{\circ}$ C
TJ	Operating Junction Temperature Range -55 to 150		$^{\circ}$ C
RθJA	Thermal Resistance Junction-Ambient 0.70		°C/W
RθJC	Thermal Resistance Junction-Case	istance Junction-Case 62 °C/W	





AP90N08NF

85V N-Channel Enhancement Mode MOSFET

Electrical Characteristics (T₁=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V(BR)DSS	Drain-source breakdown voltage	V _{GS} =0V, I _D =250uA	85	92		V
VGS(th)	Gate threshold voltage	V _{DS} =V _{GS} ,I _D =250uA T _j =25°C	2.0	3.0	4.0	V
IDSS	Zero gate voltage drain current	V _{DS} =80V,V _{GS} =0V T _j =25°C	-		1	μΑ
IDSS	Zero gate voltage drain current	V _{DS} =80V,V _{GS} =0V T _j =125°C		- 5		μΑ
IGSS	Gate-source leakage current	V _{GS} =20V,V _{DS} =0V	-	-	100	nA
RDS(on)	Drain-source on-state resistance	V _{GS} =10V, I _D =50A,T _j =25°C	-	4.5	5.2	mΩ
gfs	Transconductance	V _{DS} =5V,I _D =50A	-	80	-	S
Ciss	Input Capacitance	\/ -0\/ \/ -40\/ f-4\\ -	-	4032	-	pF
Coss	Output Capacitance	V _{GS} =0V, V _{DS} =40V, f=1MHz	-	546	-	pF
Crss	Reverse Transfer Capacitance		-	35	-	pF
Q _G	Gate Total Charge	\/=10\/\\/=40\/\-=25\	-	65.7	-	nC
Qgs	Gate-Source charge	V _{GS} =10V, V _{DS} =40V,I _D =25A	-	24.9	-	nC
Qgd	Gate-Drain charge		-	13.9	-	nC
td(on)	Turn-on delay time		-	20.1	-	ns
t _r	Rise time	T _j =25°C, V _{GS} =10V, V _{DS} =40V,	-	38	-	ns
td(off)	Turn-off delay time	- R _L =3Ω	-	45.1	-	ns
t _f	Fall time		-	21	-	ns
Rg	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz	-	2	-	Ω
VSD	Body Diode Forward Voltage	V _{GS} =0V,I _{SD} =50A	-	0.9	1.2	V
trr	Body Diode Reverse Recovery Time	I _F =20A, dI/dt=500A/μs	-	61	-	ns
Qrr	Body Diode Reverse Recovery Charge	I _F =20A, dI/dt=500A/μs	-	340	-	nC

Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2. The data tested by pulsed , pulse width .The EAS data shows Max. rating .
- 3. The test cond \leq 300us duty cycle \leq 2%, duty cycle ition is V_{DD}=64V_{GS}=10V,L=0.1mH,I_{AS}=53.8A
- 4. The power dissipation is limited by 175 ℃ junction temperature
- 5. The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.





Typical Characteristics

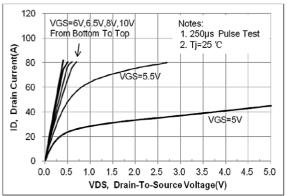


Figure 1. Typ. Output Characteristics (Tj=25 ℃)

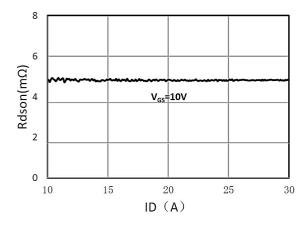


Figure 3. On-Resistance vs. Drain Current and Gate Voltage Figure

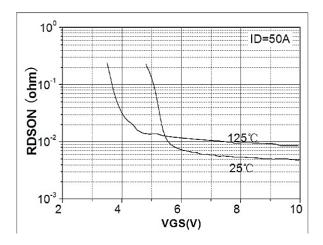


Figure 5. On-Resistance vs. Gate-Source Voltage

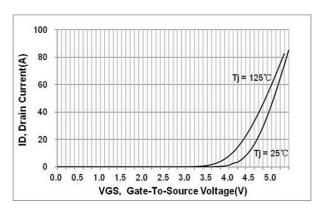


Figure 2. Transfer Characteristics

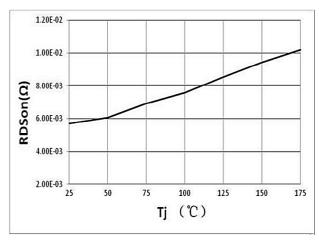


Figure 4. On-Resistance vs. Junction Temperature

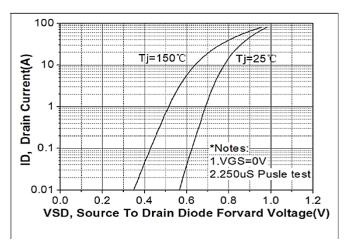
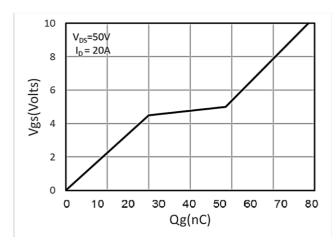


Figure 6 . Body-Diode Characteristics







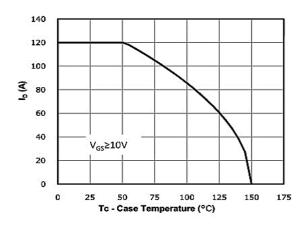


Figure 7. Gate-Charge Characteristics

Figure 8. Drain Current Derating

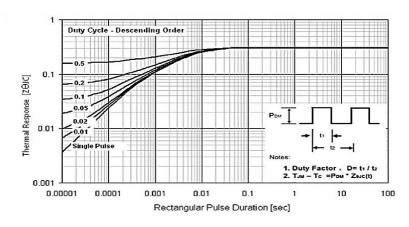


Figure 9: Normalized Maximum Transient Thermal Impedance

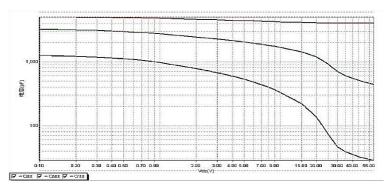
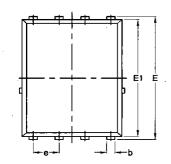


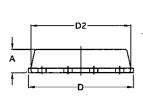
Figure 10. Capacitance Characteristics

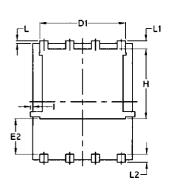


Package Mechanical Data-DFN5*6-8L-JQ Single









	Common				
Symbol	mm		Inch		
	Mim	Max	Min	Max	
Α	1.03	1.17	0.0406	0.0461	
b	0.34	0.48	0.0134	0.0189	
С	0.824	0.0970	0.0324	0.082	
D	4.80	5.40	0.1890	0.2126	
D1	4.11	4.31	0.1618	0.1697	
D2	4.80	5.00	0.1890	0.1969	
E	5.95	6.15	0.2343	0.2421	
E1	5.65	5.85	0.2224	0.2303	
E2	1.60	/	0.0630	/	
е	1.27	BSC	0.05	BSC	
L	0.05	0.25	0.0020	0.0098	
L1	0.38	0.50	0.0150	0.0197	
L2	0.38	0.50	0.0150	0.0197	
Н	3.30	3.50	0.1299	0.1378	
I	/	0.18	/	0.0070	





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85V N-Channel Enhancement Mode MOSFET

Edition	Date	Change
Rve1.0	2020/12/1	Initial release

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